Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.023 X .023”**

**.035”**

**.035”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .023” X .023”**

**Backside Potential: Cathode**

**Mask Ref: ZCD**

**APPROVED BY: DK DIE SIZE .035” X .035” DATE: 11/9/21**

**MFG: ALLEGRO / SPRAGUE THICKNESS .006” P/N: 1N5235**

**DG 10.1.2**

#### Rev B, 7/19/02